

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiao-Chun Mu et al.

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Docket No.: 884.798US1

Serial No.: 09/733,289

Filed: December 8, 2000

Due Date: September 2, 2006

Examiner: DiLinh Nguyen

Group Art Unit: 2814

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

X Amendment and Response Under 37 CFR 1.111 (14 pgs.).

X Petition for Extension of Time (1 pg.)

X Information Disclosure Statement (2 pgs.) and Form 1449 (1 pg.)

X Authorization to charge Deposit Account 19-0743 in the amount of \$120.00 to cover the Extension of Time Fee and in the amount of \$180 for the Information Disclosure Statement Fee.

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: /



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Reg. No. 40,362

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)